

CY7C1020

Features

- 5.0V operation (± 10%)
- High speed
 - —t_{AA} = 10 ns
- Low active power
- Very Low standby power
 550 μW (max., "L" version)
- Automatic power-down when deselected
- Independent Control of Upper and Lower bytes
- Available in 44-pin TSOP II and 400-mil SOJ

Functional Description

The CY7C1020 is a high-performance CMOS static RAM organized as 32,768 words by 16 bits. This device has an automatic power-down feature that significantly reduces power consumption when deselected.

 $\frac{Writing}{(CE)}$ and Write Enable (WE) inputs LOW. If Byte Low Enable

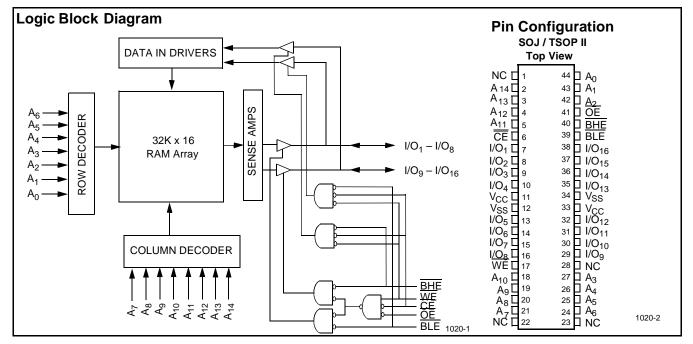
32K x 16 Static RAM

(\overline{BLE}) is LOW, then data from I/O pins (I/O₁ through I/O₈), is written into the location specified <u>on the</u> address pins (A₀ through A₁₄). If Byte High Enable (BHE) is LOW, then data from I/O pins (I/O₉ through I/O₁₆) is written into the location specified on the address pins (A₀ through A₁₄).

Reading from the device is accomplished by taking Chip Enable (\overline{CE}) and Output Enable (\overline{OE}) LOW while forcing the Write Enable (WE) HIGH. If Byte Low Enable (BLE) is LOW, then data from the memory location specified by the address pins will appear on I/O₁ to I/O₈. If Byte High Enable (\overline{BHE}) is LOW, then data from memory will appear on I/O₉ to I/O₁₆. See the truth table at the back of this data sheet for a complete description of read and write modes.

The input/output pins (I/O₁ through I/O₁₆) are placed in a high-impedance state when the device is deselected (\overline{CE} HIGH), the outputs are disabled (\overline{OE} HIGH), the BHE and BLE are disabled (\overline{BHE} , BLE HIGH), or during a write operation (\overline{CE} LOW, and WE LOW).

The CY7C1020 is available in standard 44-pin TSOP type II and 400-mil-wide SOJ packages.



Selection Guide

		7C1020-10	7C1020-12	7C1020-15	7C1020-20
Maximum Access Time (ns)		10	12	15	20
Maximum Operating Current (mA)		180	170	160	160
	L	150	140	130	130
Maximum CMOS Standby Current (mA)		3	3	3	3
	L	0.1	0.1	0.1	0.1

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3901 North First Street
San Jose
CA 95134
408-943-2600
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Maximum Ratings

(Above which the useful life may be impaired. For user guide- lines, not tested.)
Storage Temperature65°C to +150°C
Ambient Temperature with Power Applied55°C to +125°C
Supply Voltage on V_{CC} to Relative $GND^{[1]}$ –0.5V to +7.0V
DC Voltage Applied to Outputs in High Z State ^[1] 0.5V to V _{CC} +0.5V DC Input Voltage ^[1] 0.5V to V _{CC} +0.5V

Electrical Characteristics Over the Operating Range

Current into Outputs (LOW)	20 mA
Static Discharge Voltage (per MIL-STD-883, Method 3015)	>2001V
Latah Lin Ouwant	

Latch-Up Current......>200 mA

Operating Range

Range	Ambient Temperature ^[2]	v _{cc}
Commercial	0°C to +70°C	4.5V–5.5V

				7C10	20-10	7C1020-12		7C1020-15		
Parameter	Description	Test Conditions	Test Conditions		Max.	Min.	Max.	Min.	Max.	Unit
V _{OH}	Output HIGH Voltage	$V_{CC} = Min., I_{OH} = -4.0$	mA	2.4		2.4		2.4		V
V _{OL}	Output LOW Voltage	V _{CC} = Min., I _{OL} = 8.0 m	A		0.4		0.4		0.4	V
V _{IH}	Input HIGH Voltage			2.2	6.0	2.2	6.0	2.2	6.0	V
V _{IL}	Input LOW Voltage ^[1]			-0.5	0.8	-0.5	0.8	-0.5	0.8	V
I _{IX}	Input Load Current	$GND \le V_I \le V_{CC}$	$GND \leq V_{I} \leq V_{CC}$			-1	+1	-1	+1	μA
I _{OZ}	Output Leakage Current	$GND \leq V_I \leq V_{CC},$ Output Disabled		-2	+2	-2	+2	-2	+2	μA
I _{CC}	V _{CC} Operating	V _{CC} = Max.,			180		170		160	mA
	Supply Current	$I_{OUT} = 0 \text{ mA},$ $f = f_{MAX} = 1/t_{RC}$	L		150		140		130	
I _{SB1}	Automatic CE	Max. V _{CC} , <u>CE ≥</u> V _{IH}			20		20		20	mA
	$\begin{array}{l lllllllllllllllllllllllllllllllllll$		L		10		10		10	
I _{SB2}	Automatic CE	Max. V _{CC} ,			3		3		3	mA
	Power-Down Current —CMOS Inputs	$\label{eq:linear_constraint} \begin{array}{c} CE \geq V_{CC} - 0.3V, \\ V_{IN} \geq V_{CC} - 0.3V, \\ or \; V_{IN} \leq 0.3V, \; f = 0 \end{array} \right.$			100		100		100	μA

Notes:

1. V_{IL} (min.) = -2.0V for pulse durations of less than 20 ns. 2. T_A is the case temperature.



Electrical Characteristics Over the Operating Range (continued)

				7C10	20-20	
Parameter	Description	5	Min.	Max.	Unit	
V _{OH}	Output HIGH Voltage	V _{CC} = Min., I _{OH} = -4.0 mA		2.4		V
V _{OL}	Output LOW Voltage	V _{CC} = Min., I _{OL} = 8.0 mA			0.4	V
V _{IH}	Input HIGH Voltage			2.2	6.0	V
V _{IL}	Input LOW Voltage ^[1]			-0.5	0.8	V
I _{IX}	Input Load Current	$GND \leq V_I \leq V_{CC}$		-1	+1	μA
I _{OZ}	Output Leakage Current	GND <u><</u> V _I <u><</u> V _{CC} , Output Di	$GND \leq V_{I} \leq V_{CC}$, Output Disabled			μA
I _{CC}	V _{CC} Operating	V _{CC} = Max.,			160	mA
	Supply Current	$I_{OUT} = 0 \text{ mA},$ $f = f_{MAX} = 1/t_{RC}$	L		130	
I _{SB1}	Automatic CE	Max. V _{CC} , <u>CE</u> ≥ V _{IH}			20	mA
	Power-Down Current —TTL Inputs	$V_{IN} \ge V_{IH} \text{ or}$ $V_{IN} \le V_{IL}, f = f_{MAX}$	L		10	
I _{SB2}	Automatic CE	<u>Ma</u> x. V _{CC} ,			3	mA
	Power-Down Current —CMOS Inputs	$\label{eq:central_constraint} \begin{split} \overline{CE} &\geq V_{CC}^{-} - 0.3V, \\ V_{IN} &\geq V_{CC}^{-} - 0.3V, \\ \text{or } V_{IN} &\leq 0.3V, \ f = 0 \end{split}$	L		100	μA

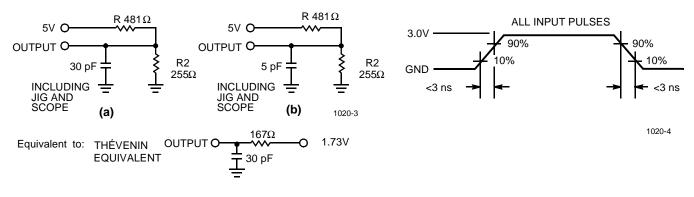
Capacitance^[3]

Parameter	Description	Test Conditions	Max.	Unit
C _{IN}	Input Capacitance	$T_A = 25^{\circ}C, f = 1 \text{ MHz},$	8	pF
C _{OUT}	Output Capacitance	$V_{CC} = 5.0V$	8	pF

Note:

3. Tested initially and after any design or process changes that may affect these parameters.

AC Test Loads and Waveforms





Switching Characteristics^[4] Over the Operating Range

		7C1020-10		7C1020-12		7C1020-15		7C1020-20		
Parameter	Description	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Unit
READ CYC	LE			•		•				
t _{RC}	Read Cycle Time	10		12		15		20		ns
t _{AA}	Address to Data Valid		10		12		15		20	ns
t _{OHA}	Data Hold from Address Change	3		3		3		3		ns
t _{ACE}	CE LOW to Data Valid		10		12		15		20	ns
t _{DOE}	OE LOW to Data Valid		5		5		7		9	ns
t _{LZOE}	OE LOW to Low Z	0		0		0		0		ns
t _{HZOE}	OE HIGH to High Z ^[5, 6]		5		6		7		8	ns
t _{LZCE}	CE LOW to Low Z ^[6]	3		3		3		3		ns
t _{HZCE}	CE HIGH to High Z ^[5, 6]		5		6		7		8	ns
t _{PU}	CE LOW to Power-Up	0		0		0		0		ns
t _{PD}	CE HIGH to Power-Down		12		12		15		20	ns
t _{DBE}	Byte enable to Data Valid		5		6		7		9	ns
t _{LZBE}	Byte enable to Low Z	0		0		0		0		ns
t _{HZBE}	Byte disable to High Z		5		6		7		9	ns
WRITE CYC	LE ^[7]			•		•				
t _{WC}	Write Cycle Time	10		12		15		12		ns
t _{SCE}	CE LOW to Write End	8		9		10		12		ns
t _{AW}	Address Set-Up to Write End	7		8		10		12		ns
t _{HA}	Address Hold from Write End	0		0		0		0		ns
t _{SA}	Address Set-Up to Write Start	0		0		0		0		ns
t _{PWE}	WE Pulse Width	7		8		10		12		ns
t _{SD}	Data Set-Up to Write End	5		6		10		10		ns
t _{HD}	Data Hold from Write End	0		0		0		0		ns
t _{LZWE}	WE HIGH to Low Z ^[6]	3		3		3		3		ns
t _{HZWE}	WE LOW to High Z ^[5, 6]		5		6		7		9	ns
t _{BW}	Byte enable to end of write	7		8		9		12		ns

Notes:

Test conditions assume signal transition time of 3 ns or less, timing reference levels of 1.5V, input pulse levels of 0 to 3.0V, and output loading of the specified I_{QL}/I_{OH} and 30-pF load capacitance. 4.

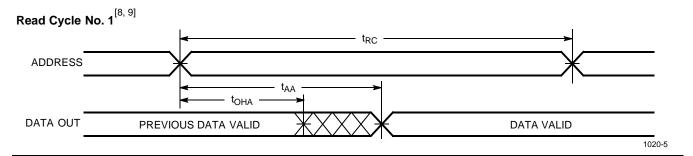
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6.

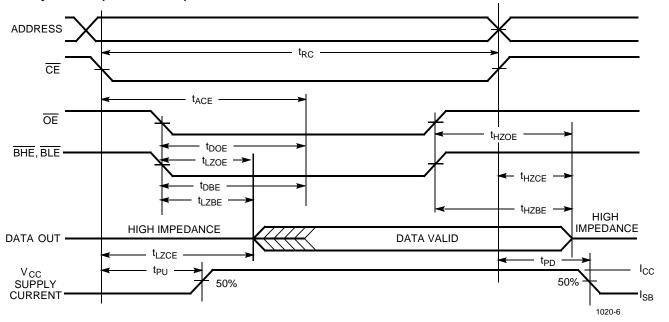
To(JOH and 30-pF load capacitation). t_{HZOE}, t_{HZDE}, t_{HZZE}, and t_{HZWE} are specified with a load capacitance of 5 pF as in part (b) of AC Test Loads. Transition is measured ±500 mV from steady-state voltage. At any given temperature and voltage condition, t_{HZCE} is less than t_{IZCE}, t_{HZOE} is less than t_{IZCE}, t_{HZOE}, and t_{HZWE} is less than t_{LZWE} for any given device. The internal write time of the memory is defined by the overlap of CE LOW, WE LOW and BHE / BLE LOW. CE, WE and BHE / BLE must be LOW to initiate a write, and the transition of these signals can terminate the write. The input data set-up and hold timing should be referenced to the leading edge of the signal that terminates the write. 7.



Switching Waveforms



Read Cycle No. 2 (\overline{OE} Controlled) ^[9, 10]



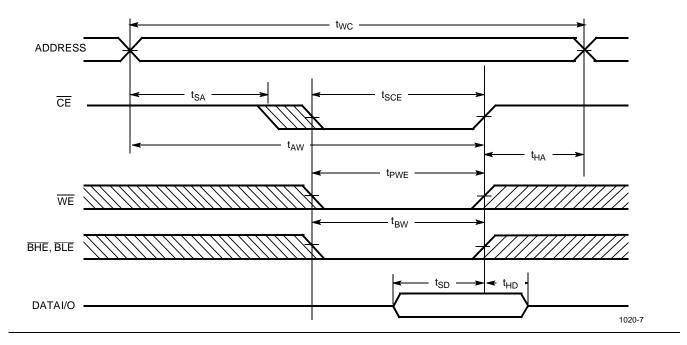
Notes:

- 8. <u>Device</u> is continuously selected. \overline{OE} , \overline{CE} , \overline{BHE} and/or $\overline{BHE} = V_{IL}$. 9. WE is HIGH for read cycle. 10. Address valid prior to or coincident with \overline{CE} transition LOW.

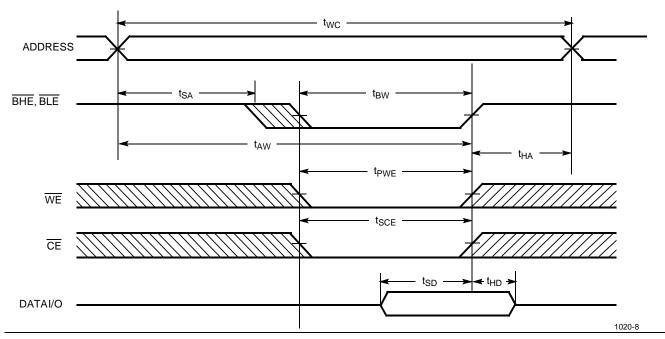


Switching Waveforms (continued)

Write Cycle No. 1 (\overline{CE} Controlled)^[11, 12]



Write Cycle No. 2 (BLE or BHE Controlled)



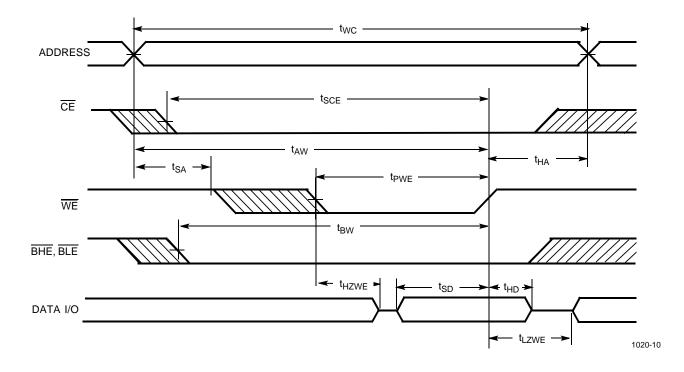
Notes:

Data I/O is high impedance if OE or BHE and/or BLE = V_{IH}.
If CE goes HIGH simultaneously with WE going HIGH, the output remains in a high-impedance state.



Switching Waveforms (continued)

Write Cycle No.3 (\overline{WE} Controlled, \overline{OE} LOW)



Truth Table

CE	OE	WE	BLE	BHE	1/0 ₁ –1/0 ₈	I/O ₉ -I/O ₁₆	Mode	Power
Н	Х	Х	Х	Х	High Z	High Z	Power-Down	Standby (I _{SB})
L	L	Н	L	L	Data Out	Data Out	Read - All bits	Active (I _{CC})
			L	Н	Data Out	High Z	Read - Lower bits only	Active (I _{CC})
			Н	L	High Z	Data Out	Read - Upper bits only	Active (I _{CC})
L	Х	L	L	L	Data In	Data In	Write - All bits	Active (I _{CC})
			L	Н	Data In	High Z	Write - Lower bits only	Active (I _{CC})
			Н	L	High Z	Data In	Write - Upper bits only	Active (I _{CC})
L	Н	Н	Х	Х	High Z	High Z	Selected, Outputs Disabled	Active (I _{CC})
L	Х	Х	Н	Н	High Z	High Z	Selected, Outputs Disabled	Active (I _{CC})

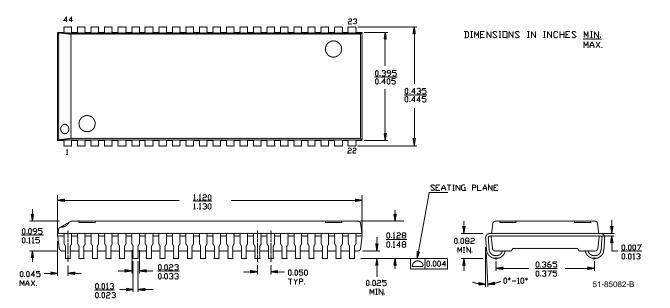


Ordering Information

Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
10	CY7C1020-10VC	V34	44-Lead (400-Mil) Molded SOJ	Commercial
	CY7C1020L-10VC	V34	44-Lead (400-Mil) Molded SOJ	Commercial
	CY7C1020-10ZC	Z44	44-Lead TSOP Type II	Commercial
	CY7C1020L-10ZC	Z44	44-Lead TSOP Type II	Commercial
12	CY7C1020-12VC	V34	44-Lead (400-Mil) Molded SOJ	Commercial
	CY7C1020L-12VC	V34	44-Lead (400-Mil) Molded SOJ	Commercial
	CY7C1020-12ZC	Z44	44-Lead TSOP Type II	Commercial
	CY7C1020L-12ZC	Z44	44-Lead TSOP Type II	Commercial
15	CY7C1020-15VC	V34	44-Lead (400-Mil) Molded SOJ	Commercial
	CY7C1020L-15VC	V34	44-Lead (400-Mil) Molded SOJ	Commercial
	CY7C1020-15ZC	Z44	44-Lead TSOP Type II	Commercial
	CY7C1020L-15ZC	Z44	44-Lead TSOP Type II	Commercial
20	CY7C1020-20VC	V34	44-Lead (400-Mil) Molded SOJ	Commercial
	CY7C1020L-20VC	V34	44-Lead (400-Mil) Molded SOJ	Commercial
	CY7C1020-20ZC	Z44	44-Lead TSOP Type II	Commercial
	CY7C1020L-20ZC	Z44	44-Lead TSOP Type II	Commercial

Package Diagrams

44-Lead (400-Mil) Molded SOJ V34



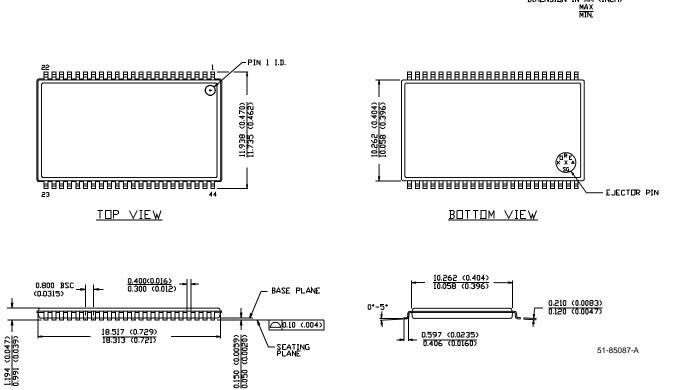


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DIMENSION IN MM (INCH)

Package Diagrams (continued)

44-Pin TSOP II Z44



SEATING PLANE

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